20th IEEE European Test Symposium
Cluj-Napoca, Romania
May 25 – 29, 2015

http://www.ieee-ets.org

Information for Prospective Corporate Supporters

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2015 European Test Symposium Corporate Support Opportunity "At a Glance"

- ETS is the annual premier European event totally devoted to test and test-synthesis of micro-electronic circuits and systems, attracting around 200 industrial and academic professionals from around the world.
- ETS 2015 will be held in Cluj-Napoca, Romania, on May 25–29, 2015.
- Your company is invited to support ETS'15 at Bronze (€1500), Silver (€2500), Gold (€5000) or Platinum (€8000) level.
- The money will be used solely to cover the costs associated with ETS, thereby attracting yet more attendees.
- In return company will get many benefits depending on the support level; examples are (a) Sponsor's name and logo on ETS web page, posters, program booklet, projection screen, and the proceedings that will be distributed to the participants, (b) Advertising space in the program booklet, (c) Advertisement e-mail to registered participant, (d) Getting priority in the selection process for the Vendor Sessions, (e) Getting priority in slot assignment for Table-Top Demo Sessions, etc.
- Since its start, ETS has been sponsored by dozens companies; examples are: Advantest, Alter, ARM, Cadence Design Systems, Eles, GÖPEL electronic GmbH, Honeywell, Infineon Technologies, Intel, JTAG technologies, Mentor Graphics, NXP Semiconductors, OptimalTest, Pintail Technologies, Preciosa, Q-Star Test, Qualcomm, Qualtera, Spea, STC, STMicroelectronics, Synopsys, SynTest, Teradyne, TestAdvantage, TestInsight, Verigy, VSystems, etc.

About ETS'15

As you probably know, the IEEE European Test Symposium (ETS) is the largest European event completely devoted to testing micro-electronic circuits and systems. ETS is organized annually in a different European country. In 2015, ETS will be held in Cluj-Napoca, Romania, and will take place May 25-29.

The ETS program comprises plenary keynotes, parallel paper sessions, vendor sessions, poster sessions, panel sessions, spring school, and fringe workshops. ETS is also renowned for its excellent Social Event and informal atmosphere, providing many opportunities for networking. ETS is annually attended by many design, design-for-test, and test professionals from companies and academia.

To find out more about ETS'15, visit http://www.ets15.ro.

Corporate Support ETS'15

Since its start, ETS have been supported by large number of word-wide companies and SMEs. The donation is solely used to cover costs associated with ETS and make the event accessible to more attendees. In return ETS gives the Sponsor different benefit *depending on* the support grade as explained in Section "ETS'15 Support Grades". These include:

- Sponsor's name and logo on ETS web page, posters, program booklet, projection screen, and the proceedings that will be distributed to the participants.
- Advertising space in the program booklet,
- Advertisement e-mail to registered participant,
- Display of company logos during session intervals,
- Opportunity to provide company hand-out material,
- Getting priority in the selection process for the Vendor Sessions,
- Getting priority in slot assignment for Table-Top Demo Sessions,
- Etc.

We therefore would like to invite your company to become a corporate supporter of ETS'15 and contribute to a successful event! Your presence at the symposium will give you an excellent opportunity to network with established and new design, test and reliability engineers.

ETS'15 Corporate Support Grades

ETS has defined four different support grades, each with different support amounts and different benefit options.
1. **Bronze**: At least €*1500*
   - Supporter's name and logo will appear in the symposium's web page, the symposium posters, and the printed programs that will be distributed to the participants.
   - *Half-page* advertising space in the program booklet for the event. The Advance Program will be available as a downloadable PDF document before the event, and the Final Program will be a hard-copy booklet handed out to all registered attendees.
   - Priority in slot assignment for the Vendor Sessions.
   - Constant exposure of company logo in a repeating presentation loop before, in-between, and after sessions.
   - The supporter will be allowed to provide branded give-away items for inclusion in the symposium registration bag.
2. **Silver**: *At least €2500*
   - As per Bronze Level, plus:
   - *Full-page* advertising space in the program booklet.
   - The supporter's name and logo will appear in the proceedings of the symposium.
   - The supporter's name and logo will appear on the symposium's registration bag.
   - Opportunity to send out *one advertisement* e-mail to registered symposium participants prior to the symposium.
3. **Gold**: *At least €5000*
   - As per Silver Level, plus:
   - A special area and/or Table Top Demo at the symposium site will be assigned to the supporter as its own demonstration area (posters, leaflets, recruitment material, and other advertisement material). This could be a table (provided by ETS) or a booth (supplied by the corporate supporter).
   - Opportunity to send out *two advertisement* e-mails to registered symposium participants prior to the symposium.
4. **Platinum**: *At least €8000*
   - This is a Main Corporate Supporter. As per Gold Level, plus:
   - *Guaranteed* slot assignment in the Vendor Sessions.
   - The support money will be used primarily for the Social Event of the workshop, which will be announced "to be offered by the Main Supporter(s)".
   - Additional publicity paths can be arranged as requested by the supporter.

Vendor Session Presentations

ETS offers commercial vendors the opportunity to give technical presentations in a track parallel to the technical paper sessions. These presentations will be listed in the symposium program along with the technical sessions, and are targeted to the ETS technical audience. The Vendor Sessions differ from standard ETS presentations in that company names, logos, and product names may be mentioned explicitly. Content could include product descriptions, case studies, best practices, and testimonials.

Presentation opportunities of 30-minutes duration are available: proposal selection is based the technical contact and relevance to the ETS audience and topics. To find out more about the Vendor Sessions, visit the ETS web site at and follow the link to Vendor Sessions, Call for Submissions, or send an e-mail requesting more information. Please note that ETS guarantee a presentation slot in the Vendor Session only for Platinum Corporate Sponsors. Nevertheless, we will do our utmost to accommodate your request taking into consideration your Corporate Support Grade and the available time slots at the symposium.

Demo Area/ Table Top Demo

ETS symposium offers a demo area and/or Table-Top Demo. You can make use of the opportunity to present/demonstrate e.g., posters, leaflets, recruitment material, advertisement material, technical descriptions, case studies, best practices, user testimonials of products or solutions, etc. These presentations will be listed in the workshop program booklet along with the regular paper sessions, and should be targeted to the Symposium technical audience. Demo Area/ Table-Top Demo differ from other symposium presentations in that a company name, logo, and product name may be mentioned explicitly.

Further information

If your company is interested to become a corporate supporter and take advantage of opportunities describe above or if you need any additional information, please contact the ETS Industrial Relations Chair, Said Hamdioui S.Hamdioui@tudelft.nl.

Affiliations of Past ETS Attendees

Advantest (Europe)	IST/INESC.ID	Technical University of Prague
Advantest America	IXL Laboratory	Teradyne, Inc.
Agilent Technologies	JHU/Applied Physics Laboratory	Test Advantage Inc
Alter Technology Group Spain	Jozef Stefan Institute	TestInsight Ltd.
AMD Corporation	KTH/ECS	Texas Instruments
Analog Devices	Kuwait University	Thales - Aerospace Division
Aptina Imaging	Kyushu Institute of Technology	Thomas Bata University
ARM Ltd	Lancaster University	TIMA
ASICentrum s.r.o.	LCIS/INPG	TNO
Atmel Norway & Rousset	Linköping University	Tokyo Metropolitan University
Atrenta Inc	LIRMM	Tsinghua University
Auburn University	LogicVision	TU Berlin
Azoteq	Loughborough University	UC San Diego
Bahcesehir University	LSI Logic Corporation	UFRGS – Univ. Federal do Rio Grande Sul
Blue Pearl Software	LTX Corporation	Universidade de Vigo
Bordeaux 1 University	MAGMA Design Corporation	Universidade Federal de Pelotas
Brno University of Technology	McMaster University	Universitat de les Illes Balears
Brown University	Mechatronyx S.r.l.	Universitat Politècnica de Catalunya
Cadence Design Systems	Melexis	Universität Freiburg
Catholic University - PUCRS	Mentor Graphics	Universität Paderborn
CEA Grenoble - LETI/DCIS/SCME	NAIST Japan	University Carlos III de Madrid
CEA LIST	NASA Goddard Space Flight Center	University College Cork
Chiba University	National Central University Taiwan	University of Alabama
Chinese Academy of Sciences	National Institute for Astrophysics	University of Algarve
Chinese University of Hong Kong	National Networked Tele Test Facility	University of Bologna
Cisco Systems Inc	National Technical University of Athens	University of Bremen
CNM - IMSE	National Tsing-Hua University Taiwan	University of Bristol
Credence Systems (UK) Ltd	National University of Defense Technology	University of Cantabria
Credence Systems Corporation	NEC Labs	University of Edinburgh
CTU Prague	Newcastle University	University of Erlangen-Nürnberg
DAFCA	Nokia Oyj	University of Freiburg
DeFacTo Technologies	Norwegian Univ. of Science and Technology	University of Hannover
Delft University of Technology	Novas Software	University of Ioannina
DMOS GmbH	NUDT	University of Iowa
Duke University	NXP Semiconductors	University of Limerick
Electronic Systems & Software IET	Optimal Test	University of Madrid
ELES Semiconductor Equipment S.p.A.	Oxford University	University of Manchester
ELMOS Semiconductor	Philips Electronics	University of Massachusetts Lowell
EPSRC	Philips Research	University of Michigan
Ericsson	Pintail Technologies	University of Newcastle Upon Tyne
ETH Zurich	Politecnico di Milano	University of Oulu
European Patent Office	Politecnico di Torino	University of Paderborn
European University of Brest	Pontificia Universidad Catolica del Peru	University of Passau
Federal University of RGS - UFRGS	Poznan University of Technology	University of Patras, Greece
FEI STU	PSA Peugeot Citroen	University of Pireaus
Focused Solutions Alliance	Purdue University	University of Potsdam
Fraunhofer IIS / EAS	Qimonda AG	University of Pretoria
Freescale Semiconductor	Q-Star Test	University of Rome
Georgia Institute of Technology	Qualcomm	University of Seville
Graz University of Technology	Renesas Electronics Europe GmbH	University of Southampton
Grenoble INP	Robert Bosch GmbH	University of Stuttgart
Hiroshima City University	Russia Academy of Science	University of Technology Poznan
Huawei Technology Co Ltd	Samsung Electronics	University of Tehran
IBM	Schlumberger SRPC	University of Texas
IHP GmbH	SEMI Europe	University of Texas at Austin
IM2NP	Semtech Ltd	University of Tokushima
IMAG	SFPengineering	University of Tokyo
IMEC	Sharif University of Technology, Iran	University of Twente
IMP GmbH	Silesian University of Technology	University of Verona
IMSE-CNM	Slovak Academy of Science	University of Waterloo, Canada
INAOE	Slovak University of Technology	University of Western Brittany
Indian Institute of Science Bangalore	SPEA S.p.A.	University of Wisconsin – Madison
Indian Institute of Technology Kharagpur	STMicroelectronics	UPMC / LIP6 / ASIM
Infineon Technologies AG	Synopsys Inc.	UTIA AV CR
Institute for Semiconductor Technology	Tallinn University of Technology	Verified Systems International GmbH
Institute of Control Sciences RAM	Technical University of Catalonia	Verigy
Intel Corporation	Technical University of Cluj-Napoca	Virage Logic
Ippon Innovation	Technical University of Liberec	Waseda University
IROC Technologies	Technical University of Vienna	Yogitech SpA